

DESCRIPTION

Available in SOT-363 package.

FEATURES

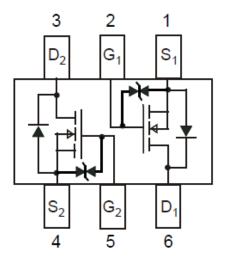
● ESD Protected: 1000V

• Available in SOT-363 package

ORDERING INFORMATION

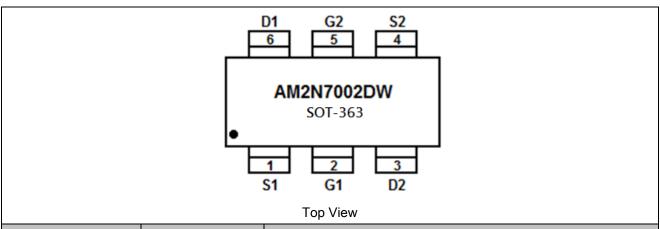
Package Type	Part Number		
SOT-363	C6	AM2N7002DWC6R	
(SC70-6)	Cb	AM2N7002DWC6VR	
	V: Halogen free Package		
Note	R: Tape & Reel		
	SPQ: 3,000pcs/Reel		
AiT provides all RoHS products			
Suffix " V " means Halogen free Package			

N CHANNEL MOSFET



MOSFET 60V SMALL SIGNAL DUAL N-CHANNEL MOSFET

PIN DESCRIPTION



Pin#	Symbol	Function	
1	S1	Source1	
2	G1	Gate1	
3	D2	Drain2	
4	S2	Source2	
5	G2	Gate2	
6	D1	Drain1	

ABSOLUTE MAXIMUM RATINGS

V _{DSS} , Drain-Source Voltage	60Vdc
V_{DGR} , Drain-Gate Voltage (R _{GS} = 1.0MΩ)	60Vdc
Drain Current	
I _D , Continuous T _C = 25°C NOTE1	±115mAdc
T _C = 100°C NOTE1	±75mAdc
I _{DM} , Pulsed NOTE2	±800mAdc
Gate-Source Voltage	
V _{GS} , Continuous	±20Vdc
V _{GSM} , Non−repetitive (tp ≤ 50μs)	±40Vpk

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

Parameter	Symbol	Max.	Unit
Total Device Dissipation	P _D	380	mW
Per Device		250	
FR-5 Board NOTE1			
T _A = 25°C			
Derate above 25°C		3.0	mW/°C
Thermal Resistance, Junction to Ambient	R _{0JA}	328	°C/W
Junction and Storage Temperature Range	TJ, TSTG	-55 to + 150	°C

ELECTRICAL CHARACTERISTICS

T_A = 25°C, unless otherwise specified

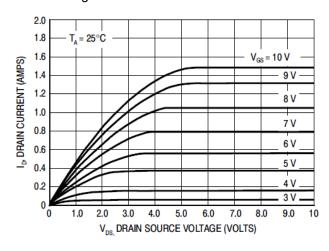
Parameter	Symbol	Conditions		Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0$, $I_D = 10 \mu Adc$		60	-	-	Vdc
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0,	T _J = 25°C	1	-	1.0	μAdc
		V _{DS} = 60Vdc	T _J = 125°C	-	-	500	
Gate-Body Leakage Current,	loose	I _{GSSF} V _{GS} = 20Vdc				1	μΛda
Forward	IGSSF			-	-	1	μAdc
Gate-Body Leakage Current,	I _{GSSR}	V _{GS} = -20Vdc		-	_	-1	μAdc
Reverse	100011						μπασ
ON CHARACTERISTICS NOTE2	T	1					
Gate Threshold Voltage	V _{GS(TH)}	$V_{DS} = V_{GS}$, $I_D = 250\mu Adc$		1.0	-	2.0	Vdc
On-State Drain Current	I _{D(ON)}	V _{DS} ≥ 2.0V _{DS(ON}	$V_{DS} \ge 2.0V_{DS(ON)}, V_{GS}=10Vdc$		-	-	mA
Static Drain–Source	V _{DS(ON)}	V _{GS} = 10Vdc, I _D	= 500mAdc	-	-	3.75	Vdc
On-State Voltage	V DS(ON)	V_{GS} = 5.0Vdc, I_D = 50mAdc		-	-	0.375	Vdc
		V_{GS} = 10 V ,	T _J = 25°C	ı	-	7.5	
Static Drain–Source	Proven	I _D = 500mAdc	T _J = 125°C	-	i	13.5	Ohms
On-State Resistance	R _{DS(ON)}	$V_{GS} = 5.0 Vdc,$	T _J = 25°C	-	i	7.5	Offilis
		I _D = 50mAdc	T _J = 125°C	-	-	13.5	
Forward Transconductance	g FS	V _{DS} ≥2.0V _{DS(ON)} ,I _D =200mAdc		80	-	-	mS
DYNAMIC CHARACTERISTICS							
Input Capacitance	Ciss	V _{DS} = 25Vcd,		-	-	50	
Output Capacitance	Coss	V _{GS} = 0,		-	-	25	pF
Reverse Transfer Capacitance	C _{RSS}	f = 1.0MHz		-	-	5.0	
SWITCHING CHARACTERISTICS	NOTE2	T				T	
Turn-On Delay Time	t _{d(ON)}	V_{DD} = 25Vdc , I_D \cong 500mAdc, R_G = 25 Ω , R_L = 50 Ω , V_{GEN} = 10V		-	-	20	ne
Turn-Off Delay Time	t _{d(OFF)}			-	-	40	ns
BODY-DRAIN DIODE RATINGS							
Diode Forward On-Voltage	V _{SD}	I _S = 115mAdc, V _{GS} = 0V		-	-	-1.5	Vdc
Source Current Continuous	Is	Body Diode		-	-	-115	mAdc
Source Current Pulsed	lsм			-	-	-800	mAdc

NOTE1: FR-5 = 1.0 x 0.75 x 0.062 in

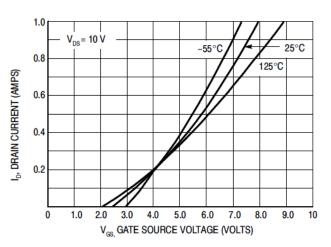
NOTE2: Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

TYPICAL PERFORMANCE CHARACTERISTICS

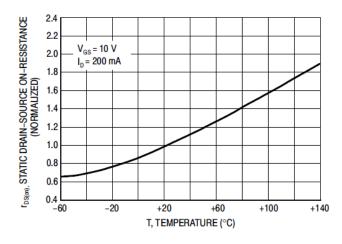
1. Ohmic Region



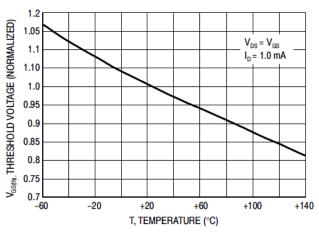
2. Transfer Characteristics



3. Temperature vs. Static Drain-Source On-Resistance

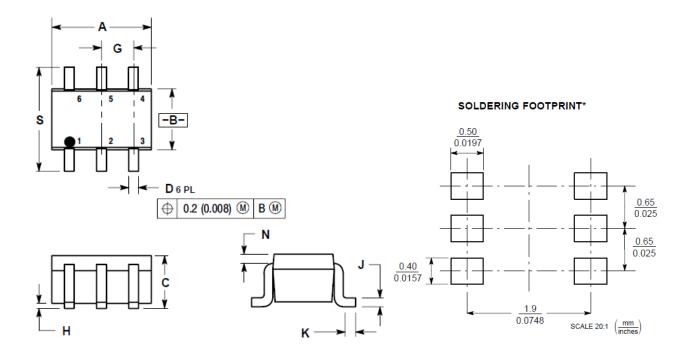


4. Temperature vs. Gate Threshold Voltage



PACKAGE INFORMATION

Dimension in SOT-363 (SC70-6) Package (Unit: mm)



SYMBOL	MIN	MAX	
Α	1.800	2.200	
В	1.150	1.350	
С	0.800	1.100	
D	0.100	0.300	
G	0.650 BSC		
Н	-	0.100	
J	0.100	0.250	
K	0.100	0.300	
N	0.200 REF		
S	2.000	2.200	

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